L Number	Hits	Search Text	DB	Time stamp
1	44	power adj laminate	USPAT; EPO; JPO; DERWENT; USOCR	2004/03/15 10:13
2	22	interposer with (power adj (layer or plane))	USPAT; EPO; JPO; DERWENT; USOCR	2004/03/15 10:17
3	19	("4489364" | "4811082" | "4840924" | "4862243" | "4984054" | "5011067" | "5049969" | "5107586" | "5220490" | "5260597" | "5294754" | "5331195" | "5414637" | "5465004" | "5473196" | "5475236" | "5502333" | "5529950" | "5786628").PN.	USPAT	2004/03/15 10:16
4	2643	(power adj (layer or plane))	USPAT; EPO; JPO; DERWENT; USOCR	2004/03/15 10:18
5	26201	(ground adj (layer or plane))	USPAT; EPO; JPO; DERWENT; USOCR	2004/03/15 10:18
6	1085	((power adj (layer or plane))) and ((ground adj (layer or plane)))	USPAT; EPO; JPO; DERWENT; USOCR	2004/03/15 10:18
7	928	(((power adj (layer or plane))) and ((ground adj (layer or plane)))) and (chip or IC or die or component)	USPAT; EPO; JPO; DERWENT; USOCR	2004/03/15 10:18
8	873	((((power adj (layer or plane))) and ((ground adj (layer or plane)))) and (chip or IC or die or component)) and (board or substrate)	USPAT; EPO; JPO; DERWENT; USOCR	2004/03/15 10:28
9	539	(((((power adj (layer or plane))) and ((ground adj (layer or plane)))) and (chip or IC or die or component)) and (board or substrate)) and @pd<20010316	USPAT; EPO; JPO; DERWENT; USOCR	2004/03/15 10:28